

ABSTRACT

2 A thin type camera module includes a fixing board, an imaging-sensing
3 semiconductor assembly, and a lens holder. The image-sensing semiconductor assembly
4 is manufacture by a chip-on-film (COF) packaging method. The image-sensing
5 semiconductor assembly comprises an image sensing chip and a COF wiring film,
6 wherein the image sensing chip is flip-chip mounted on the COF wiring film. A
7 photosensitive surface of the image sensing chip is corresponding to a window of the
8 COF wiring film and disposed toward a light-pervious channel of the lens holder. The
9 lens holder is connected with the fixing board to form an airtight space for sealing the
10 image sensing chip. The COF wiring film has a module circuit for mounting an
11 electrical device.

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